IEEE Guide for Open Access Publications

Navigating the publication process from submission to acceptance to funding





Before we start

開放研究 與 開放出版



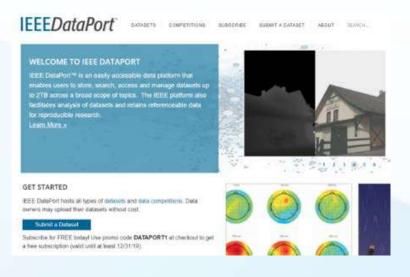
IEEE Supports Open Science (開放研究) and Reproducible Research

In addition to the full-text article, users also want access to data and research artifacts to try to reproduce the results and see if the hypothesis holds. So IEEE introduced:

- Code Ocean Allows authors to publish code or algorithms associated with research articles in a computable environment and linked to IEEE Xplore. Authors can upload code free of charge and users can access code without a subscription.
- IEEE DataPort Enables authors to publish large data sets associated with their research. Limited time promo allows users to upload an Open Access Dataset at no cost.
- TechRxiv IEEE launched a new preprint server for engineering and technology, a service that lets authors post early and fully open versions of their articles, prior to peer review and prior to being published.

These enhancements improve the extent IEEE can help researchers communicate the value of their research by facilitating the communication and availability of their research findings online.







IEEE's Evolving Open Access (開放出版)Program

To help authors gain maximum exposure for their groundbreaking research and application-oriented articles, IEEE offers three options for open access (OA) publishing, all designed to meet the varying needs of our authors throughout their careers.

OA Publishing Options

- Hybrid Journals: 100+ journals spanning an array of technology fields
- 2. Multidisciplinary OA journal IEEE *Access*®
- 3. Fully Open Access Topical Journals
 - 20 journals available now
 - Plus new journals coming soon

With these successful titles, IEEE has published thousands of open access articles in IEEE *Xplore*. And IEEE recently announced new Open Access options for authors.



IEEE Access Journal

(htoltidisciplinary)

Journals that support.

Open Access (Hybrid)

Technically Focused

Journals (Fully Open)



IEEE's Open Access Program Evolves

IEEE's publishing program continues to grow and evolve for both subscription journals and Open Access titles. IEEE continues to provide more options and choices to support the work and needs of all authors - those who prefer to publish in traditional subscription journals or those who prefer or are required to publish via Open Access.

To provide even more options for authors, IEEE has launched new gold fully open access journals spanning a wide range of technologies including



More information on these new titles now available on open.ieee.org



議程安排:

- Glossary of common terms (名詞解釋)
- Author Process for IEEE OA Submission with APC (OA 作者流程)
 - Submission process
 - Post acceptance
 - RightsLink for Scientific Communications
- Monitor the publishing activity in my institution (關注本校發表狀態)
- Resources for more information (幫助信息)



Glossary of Terms in this Guide

- APC: Article Processing Charge for an open access publication. Can be paid by the author or by the institution. Some institutions pay for APCs in advance.
- CC BY: Creative Commons By Attribution license. A CC BY license lets others distribute, remix, adapt, and build upon your work, even commercially, as long as they credit you for the original creation.
- **ECF:** IEEE's Electronic Copyright Form. Completing an eCF is a required step in all IEEE journal submissions. Authors confirm the work is original, and, for OA, agree to pay the APC and sign a CC BY license
- Hybrid Journal: A journal which accepts OA, but also publishes non-OA, subscription-based articles.
- OA Only Journal (sometimes called "Gold OA"): A fully open access journal, 100% supported by author publication fees.
- Ringgold: Database which assigns organizations and consortia a unique identifier (Ringgold ID) for scholarly communication.
- Submitting Author: An author who submits all forms and communications with IEEE. Usually the same as "Corresponding Author."
- **RLSC**: Copyright Clearance Center's RightsLink for Scientific Communications. IEEE authors will be prompted to enter final institutional funding information into RLSC as a final step before OA publication.



Submission Process – OA vs. Hybrid

- The corresponding author completes the submission process,
- OA Only journals only publish open access articles. Authors submitting to OA-only journals must confirm their agreement to the OA charges during the first step of the submission process.
- Hybrid journals allow authors the option to choose whether they would like their article to be OA or not. Authors submitting to hybrid journals will be asked to make their OA choice after acceptance, during the submission of final materials.



Choosing Where to Submit

IEEE Publication Recommender helps authors find the most suitable journal and displays journal's OA Status with submission URL

IEEE Publication Recommender[™] **∲IEEE** Find the best match for your scholarly article Search 190+ periodicals and 1800+ conferences Get all the key data about IEEE publications at a glance · Download the results of your search Compare critical points such as Impact Factor and Submission-To-Publication Time **IEEE** Publication Recommender **IEEE** Choose a search type and let Publication Recommender do the work! Periodical: Electron Devices Society, IEEE Journal of the Enter keywords, key phrases, or article title Extract keywords Both Periodicals and Conferences. Open Access Availability: Impact Factor: 2 Open Access Only Electron Devices Enter your abstract Periodicals only Eigenfactor: 0.00259 here (PDF, DOC, E Submission to Publication in Xplore: Not yet Conferences only Article Influence Score: 0 0.764 available Issues per year: 1 PERIODICALS Electron Devices, IEEE Transactions on Narrow by date: Published By: Not yet available I wo Electron Devices Society, IEEE Journal of the (Optional) Electron Device Letters, IEEE The IEEE Journal of the Electron Devices Society (J-EDS) is an open-Go to https://ieeexplore.ieee.org/xpl/RecentIssue.jsp?punu access, fully electronic scientific journal publishing papers ranging from Periodical mber=6245494 CONFERENCES fundamental to applied research that are scientifically rigorous and home page: relevant to electron devices. The J-EDS publishes original and significant 2020 IEEE International Electron Devices Meeting contributions relating to the theory, modelling, design, performance, Contact: Not yet available and reliability of electron and ion integrated circuit devices and Or, find details for a specifi 2021 IEEE International Electron Devices Meeting (IEDM) Enter the name of a periodical or conference 2023 International Electron Devices Meeting (IEDM) 2022 International Electron Devices Meeting (IEDM) 2024 IEEE International Electron Devices Meeting

Note: Open Access status clearly displayed in results.

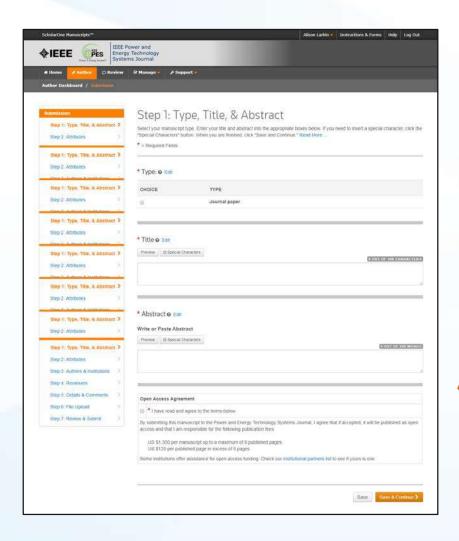
Submission process – Step 1

Once the author has chosen the appropriate publication, they will use the journal's submission system to submit the article for review.

- ✓ OA Only Journal: Step 1 of the submission process for OA-Only journals will require agreement to OA charges.
- ☐ Hybrid Journals will not require agreement to OA charges. OA agreements will come after paper has been accepted for future publication.



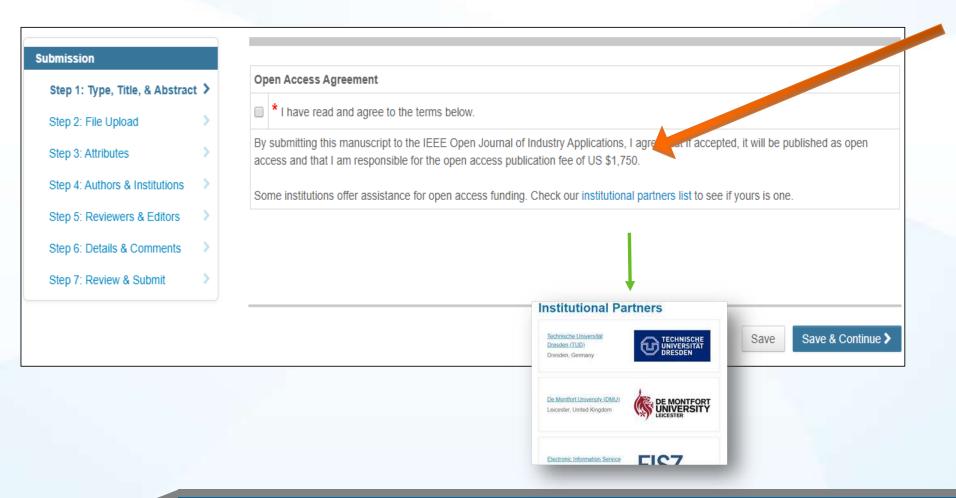
Step 1 of Submission to an OA Only Journal (Example 1)







Step 1 of Submission to an OA Only Journal (Example 2)



Open Access agreement is present.

Note: There is some Open Access pricing variation among journals.

Detailed article processing charge (APC) information can be found at https://open.ieee.org/index.php/for-authors/article-processing-charges/.



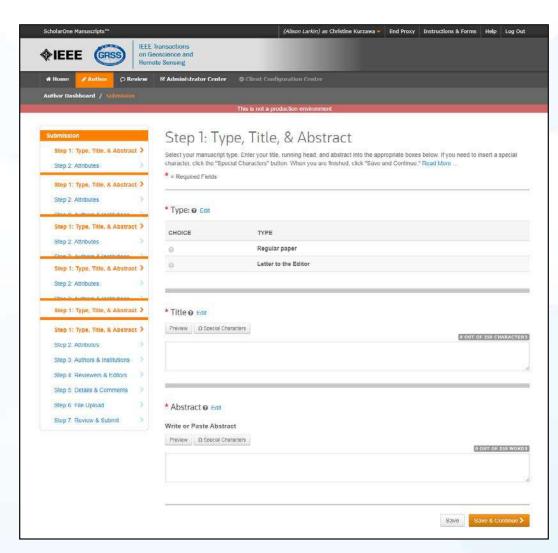
Submission process – Step 1

- □ OA-Only Journal: Step 1 of the submission process for OA-Only journals will require agreement to OA charges.
- ✓ Hybrid Journals will not require agreement to OA charges. OA agreements will be made after paper has been accepted for future publication.



Step 1 of Submission to a Hybrid journal

Note: Open Access agreement is not present on submission form.





Submission process – Step 2

- After Step 1, the submission process for Hybrid and OA Only journals follow the same path.
- General requirements may vary journal to journal, but there are several key elements that are important to complete at this time to ensure proper Open Access processing later during publication
 - Assigning Authors
 - Identifying Institution
 - Entering Funding Information



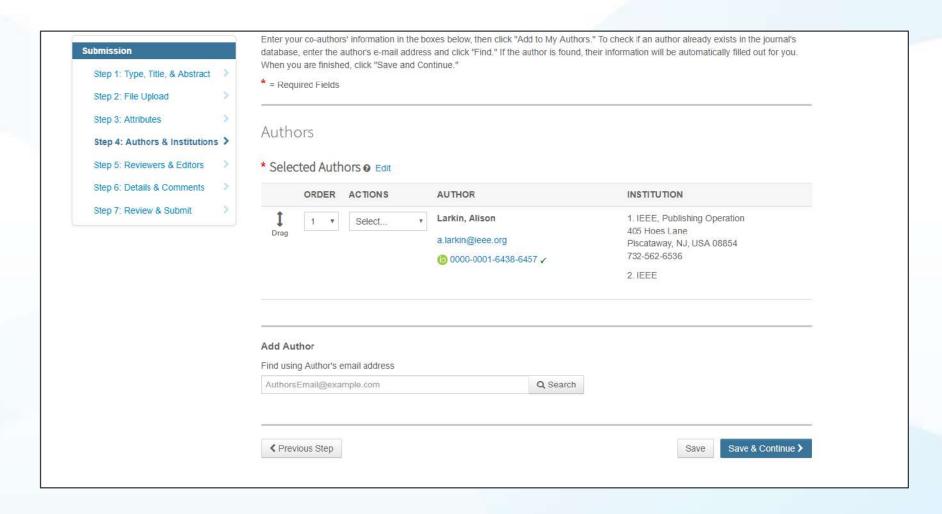
Adding Authors During Submission

The submitting author enters all co-author information.

If the co-author does not have an account, the submitting author will create one, and add institution data.

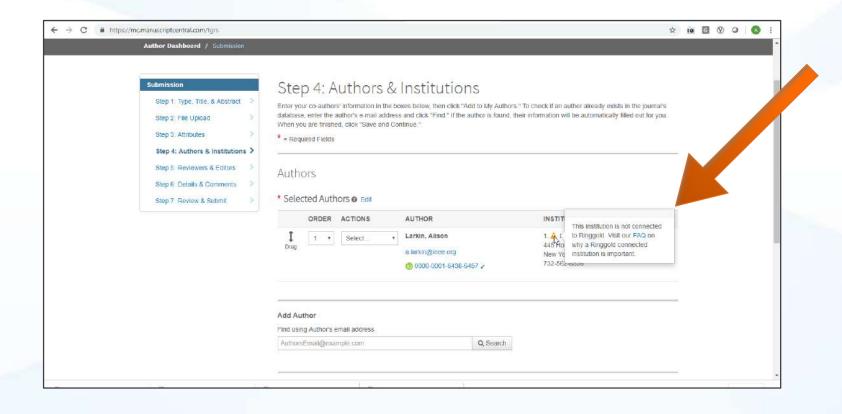
The submitting author's institution data will be used to match the author with their institutional OA account.

Note: Some institutions will not fund publication if their institution is not listed first.





Matching Author Institution with Ringgold

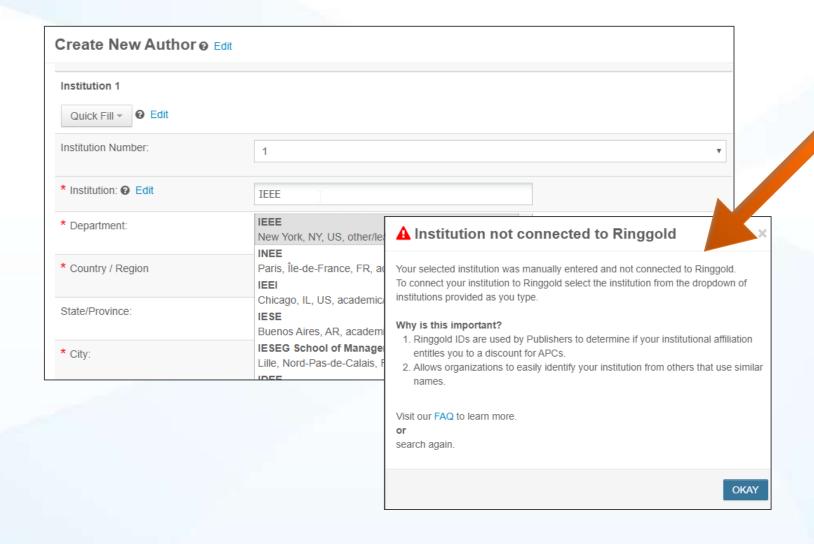


Ringgold identifiers are a list of standardized institution names and corresponding institutional IDs.

This ID is used by publishers to match an author's affiliation to any APC accounts that the institution has prepurchased.



Connecting Ringgold During Submission



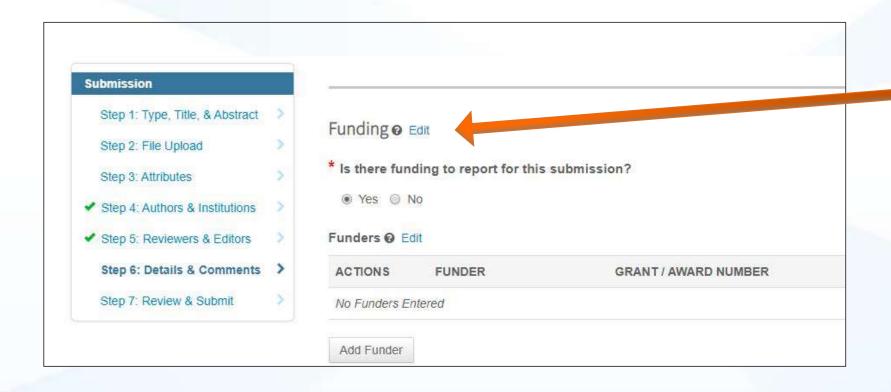
Ringgold IDs are integrated in the submission system.

When adding an author's institution information, the system will present the author with a list of institutions that most closely match what the author has entered.

If the author does not tie the affiliation to a Ringgold, a warning message appears.



Entering Funding Information at Submission



The submitting author will be required to disclose any funding information during submission.

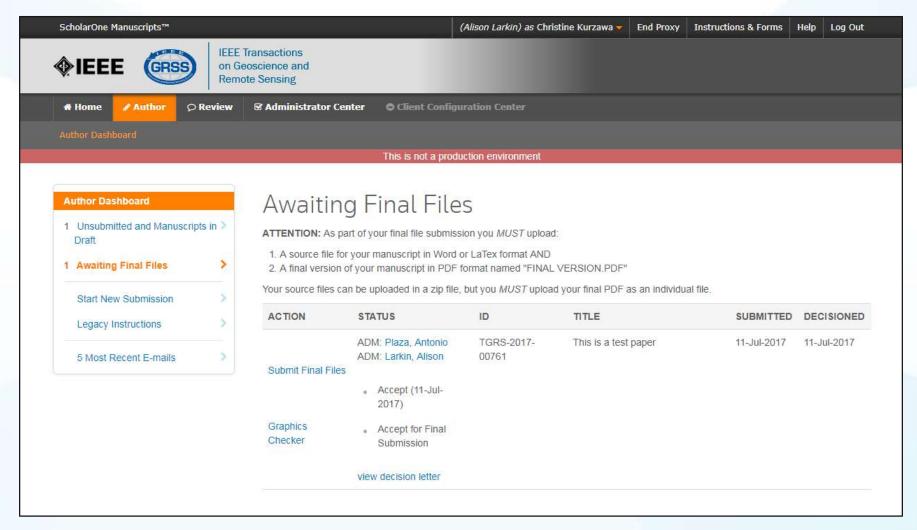


Step 3 – Acceptance and Post-Acceptance tasks

- If the manuscript is accepted, the author will be prompted to upload the final files and choose a copyright license.
- After acceptance, Hybrid Journal authors may choose whether to publish Open Access.



Post-acceptance: final file upload





Post acceptance: Hybrid Journal review

Open Access

* This publication is a hybrid journal, giving authors the choice of making their article freely accessible to users by paying an open access article processing charge (APC), or choosing traditional article publication, allowing access to users through subscription and other purchasing options. Now that your article has been accepted for publication you may enable unrestricted public access by selecting "yes" below. If you select yes, you commit to pay the US \$2,045 APC.

Although voluntary page charges do not apply to open access article submissions, other applicable charges (such as over-length paper charges or a charge for the use of color in print format) will be billed separately once article formatting is complete (but prior to publication). Over-length paper charge details can be found here.

Some institutions offer assistance for open access funding. Check our institutional partners list to see if yours is one.

For any questions regarding IEEE open access policies, please refer to our Frequently Asked Questions on open access.

- Yes please make my article Open Access. I will pay the \$2,045 APC, as well as any other applicable charges as outlined above.
- No my article is a traditional submission. I understand that over-length paper charges or color charges may still apply, as outlined above.

Note: Author of papers accepted in Hybrid Journals are only asked about Open Access after acceptance, during the submission of final materials.



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Dresden, Germany

De Montfort University (DMU)
Leicester, United Kingdom

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Save & Continue >



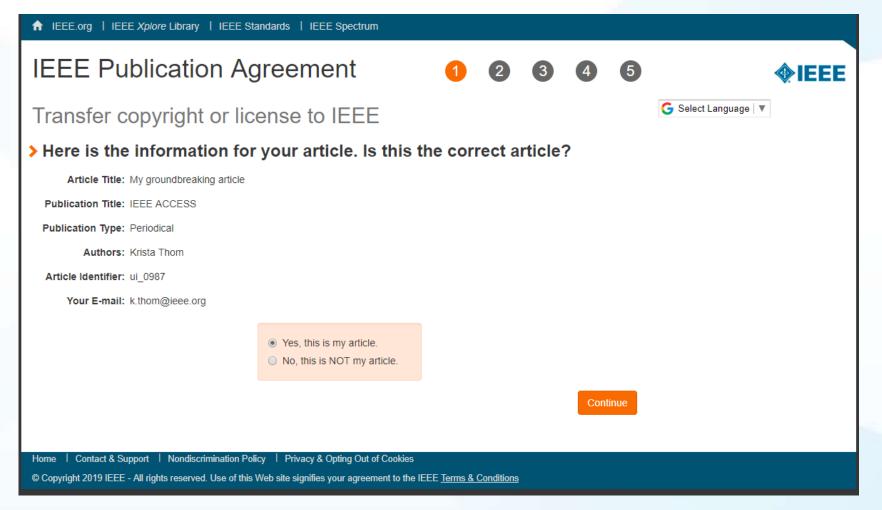
Post acceptance – copyright selection

- After acceptance, authors will be prompted to choose their copyright license using the Electronic Copyright Form (eCF).
- Authors publishing in hybrid journals may choose between:
 - Traditional publishing: a traditional license (in which copyright is transferred to the publisher and the article is published behind a paywall), or
 - Open Access publishing: A CC BY 4.0 license (in which the author retains copyright and the article is published open access).
- Authors publishing in OA Only journals will be prompted to choose CC BY.



eCF - step 1

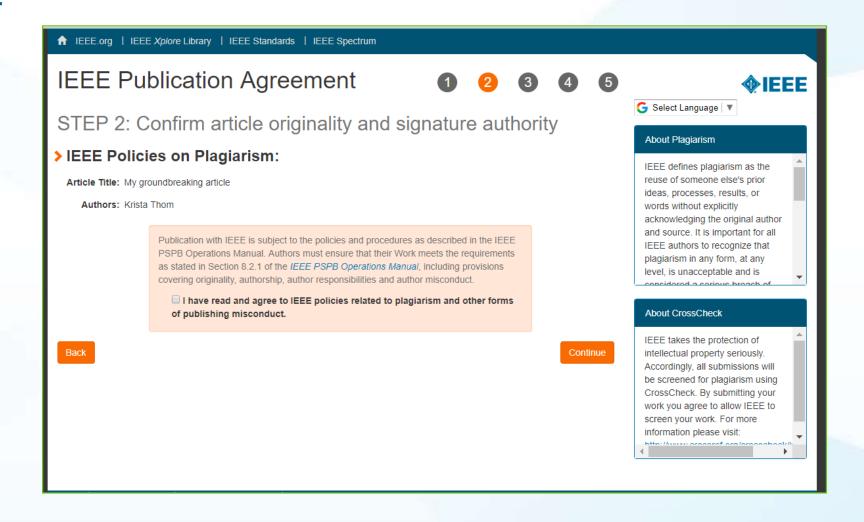
In step 1, authors confirm that the article details are correct.





eCF - step 2

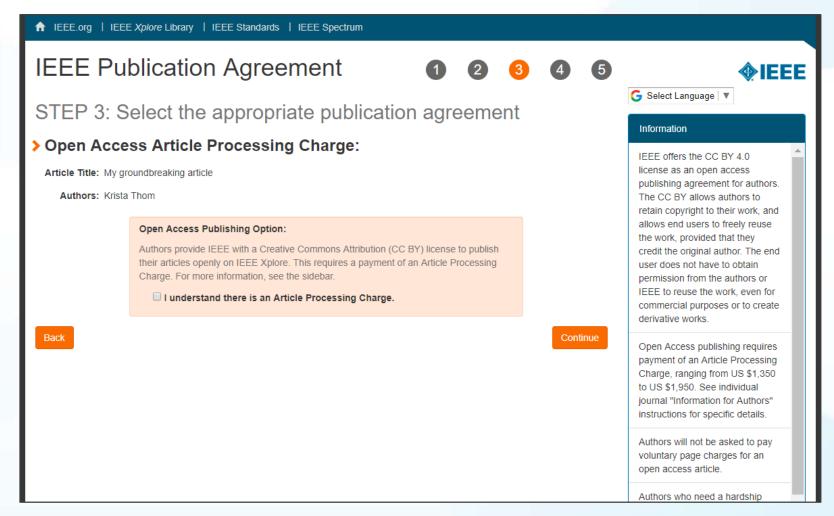
In step 2, the author confirms the paper's originality.





eCF - step 3

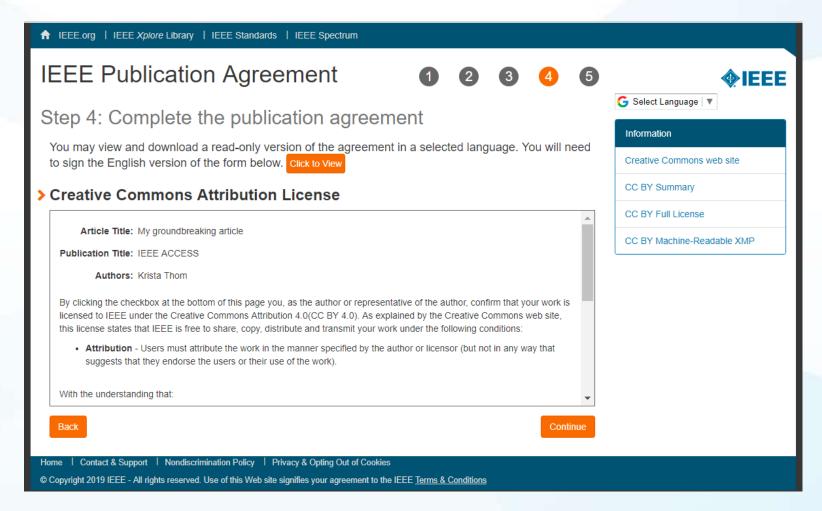
Authors of Open Access articles must agree to pay an article processing charge (APC).





eCF – step 4

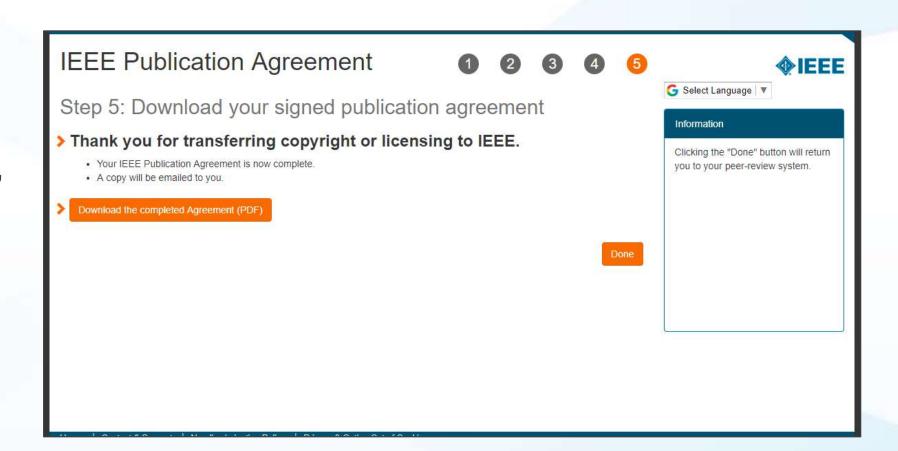
Authors of Open Access articles are prompted to sign the CC BY 4.0 license.





eCF – step 5

After the author has submitted an electronic signature, they will be able to download a copy of the license agreement.



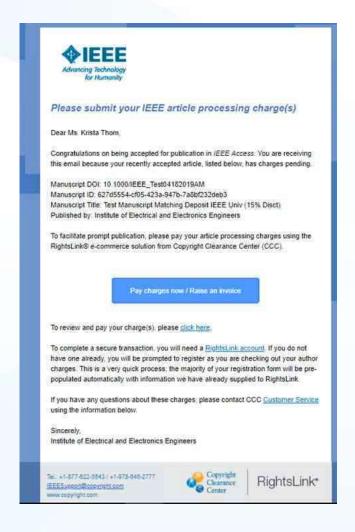


Step 4: Paying for publication using an APC

- All IEEE article processing charges (APCs) are handled through RightsLink for Scientific Communications (RLSC).
- After submitting the eCF and indicating Open Access, authors will receive an email prompting them to pay all charges through RLSC.
- If the submitting author is affiliated with an institution that has an OA agreement, they will be prompted to seek funding from that institution.
 - Institutional profiles are matched using author-provided affiliation data and Ringgold IDs.
 - In some cases, the author's email domain may also be used as a matching criterion.



Acceptance notification from RightsLink



Upon acceptance, authors will receive a notification email prompting them to pay charges through RLSC.



Please submit your IEEE article processing charge(s)

Dear Ms. Krista Thom,

Congratulations on being accepted for publication in *IEEE Access*. You are receiving this email because your recently accepted article, listed below, has charges pending.

Manuscript DOI: 10.1000/IEEE_Test04182019AM

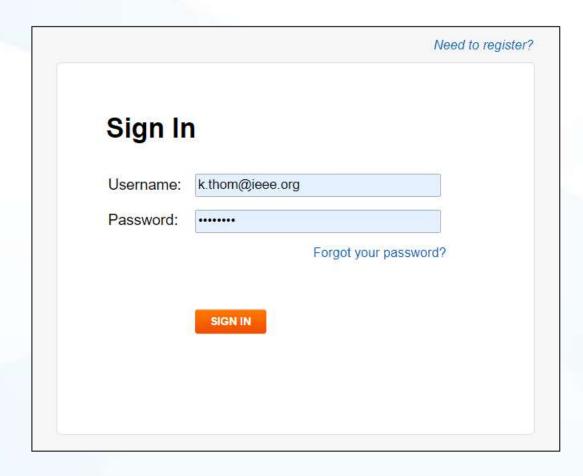
Manuscript ID: 627d5554-cf05-423a-947b-7a8bf232deb3

Manuscript Title: Test Manuscript Matching Deposit IEEE Univ (15% Disct)

Published by: Institute of Electrical and Electronics Engineers

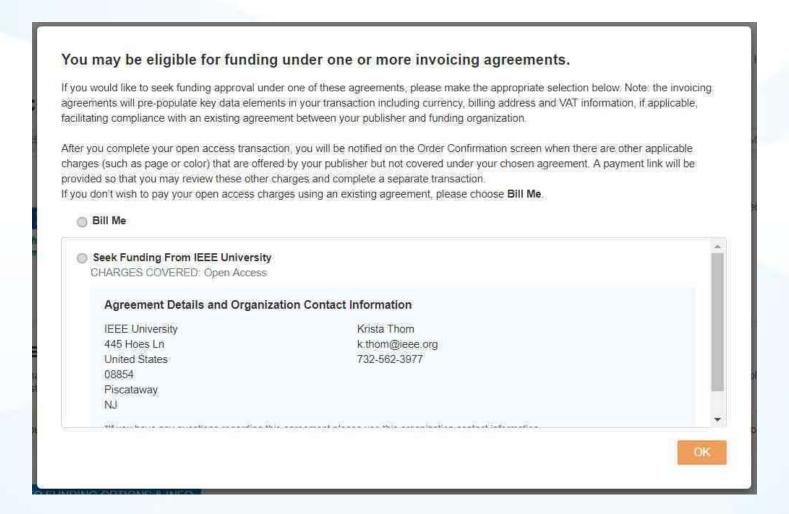
To facilitate prompt publication, please pay your article processing charges using the RightsLink® e-commerce solution from Copyright Clearance Center (CCC).





RightsLink is managed by Copyright Clearance Center and not by IEEE. Authors will need to create a separate RightsLink account to view or pay charges.

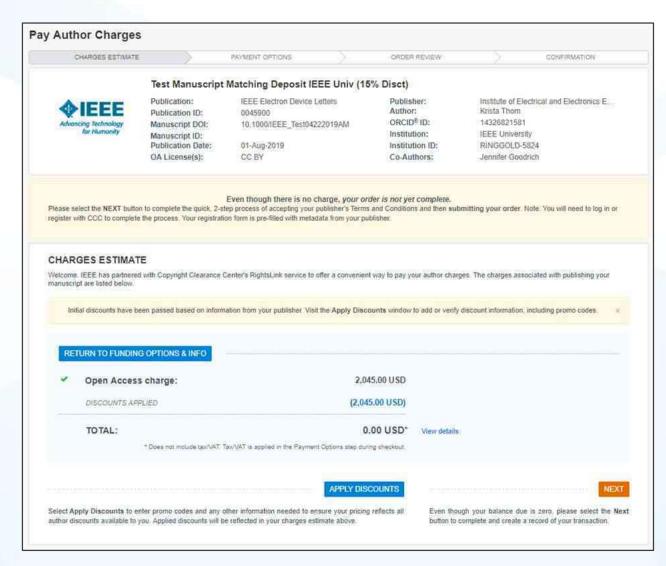




If the affiliation data entered by an author matches an existing institutional profile, authors will see a pop-up prompting them to seek funding from their institution.

If an author chooses "Bill Me" instead, they will go through the standard workflow, and will not use institutional funds.

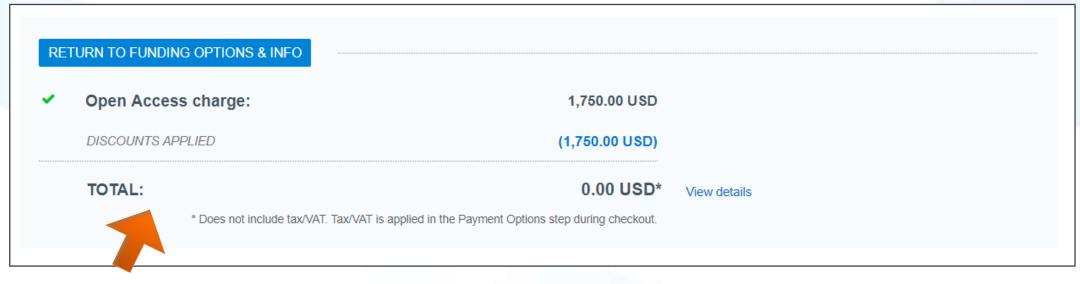




After the author chooses a payment method, they will see a summary of the charges, including any discounts.

Note that authors must complete the checkout process, even for \$0 orders.





View of charges if the author seeks funding from their institution. (Discounts may vary depending on the agreement.)

View of charges if the author selects "Bill Me."



Open Access charge:

1,750.00 USD

TOTAL:

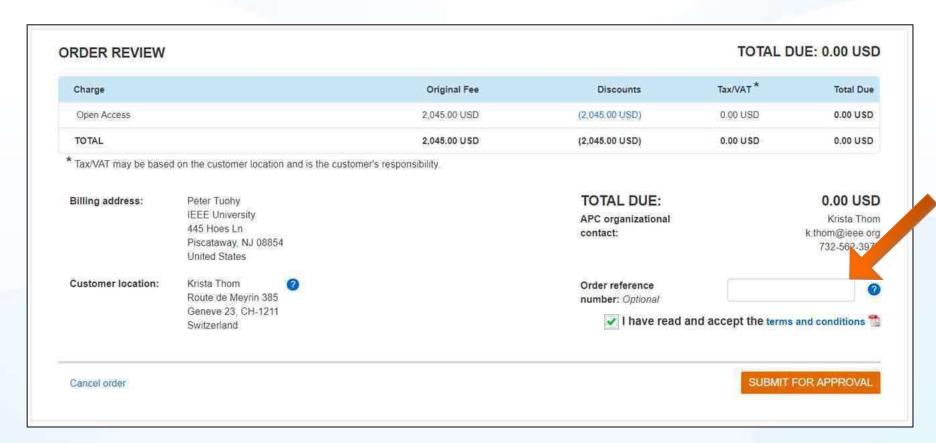
1,750.00 USD*

View details

* Does not include tax/VAT. Tax/VAT is applied in the Payment Options step during checkout.



Next, the author will review their order and accept the terms and conditions. If all details are correct, they will click "SUBMIT FOR APPROVAL."



If a PO or other tracking number is needed, the author will enter it here.



ORDER CONFIRMATION

Print Friendly Format

Order number: Not available until funding is approved.

TOTAL DUE: 0.00 USD

Order date: 23-Apr-2019

Thank you for your order! We have requested funding approval from your institution.

If approved, you will receive a request confirmation email with your order number.

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Charge	Original Fee	Discounts	Tax/VAT *	Total Due
Open Access	2,045.00 USD	(2,045.00 USD)	0.00 USD	0.00 USD
TOTAL	2,045.00 USD	(2,045.00 USD)	0.00 USD	0.00 USD

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Billing address: Peter Tuohy

IEEE University 445 Hoes Ln

Piscataway, NJ 08854

United States

Customer location: Krista Thom

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Geneve 23, CH-1211

Switzerland

TOTAL DUE:

APC organizational contact:

k.thom@ieee.org 732-562-3977

Terms and conditions 📆

0.00 USD

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After submitting their order, the author will see a confirmation page.



如何關注本校OA發表狀態



IEEE會定期推送貴校OA發表狀態的Report

- A report that IEEE can provide to NCHU on a quarterly basis.
- List of OA published papers with almost all field information, such as title, authors, affiliations, DOI,



Search and setting IEEE Xplore alerts

- Many administrators want to monitor the publishing activity from their institution.
- They can do this by searching or setting up alerts in IEEE Xplore.



Searching for published articles

Administrators can search IEEE Xplore for articles by affiliation and/or by funding agency. They can also set alerts.



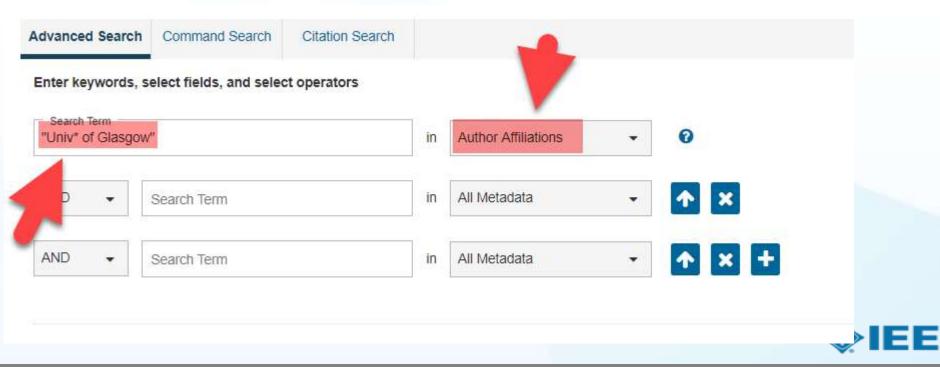


On the IEEE Xplore homepage, click on "Advanced Search."





- Select "Author Affiliation" from the dropdown menu, and enter the relevant search term.
- It is a good idea to also include alternate spellings or abbreviations in the search.



Searching by funding agency

- Funding agencies can also be added as a search parameter.
- When performing an advanced search, select "Funding Agency" from the dropdown menu.
- Be sure to use the correct Boolean operators when a search includes multiple parameters.

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Color versions of one or more of the figures in this paper are available online at http://ieeexplore.ieee.org.

Digital Object Identifier 10.1109/TNANO.2017.2665691

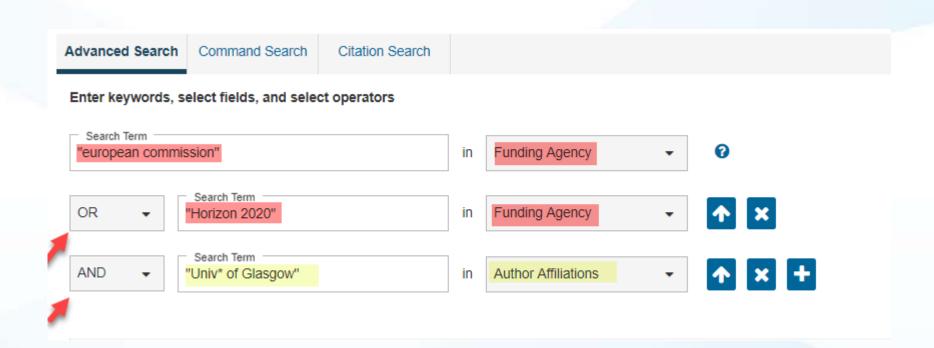
1D nanowire system) where the transistor functionality will be preserved. Also we demonstrate by moving to 1D, a Si nanowire doped well above the 3D insulator-metal transition with high $I_{\rm OR}$ whilst simultaneously providing excellent electrostatic control for a low $I_{\rm OH}$ and a ratio between the two of 10^8 .

Conventional MOSFETs running in inversion have a drain current, I_D , that improves with reduced gate-length L_g , since $I_D \propto \frac{\mu}{L_g} (V_g - V_T)^2$ where μ is the mobility, V_g is the gate voltage and V_T is the threshold voltage. As the dimensions of these conventional transistors are reduced, however, higher doping in the channel is required to suppress short channel effects, which in turn reduces the mobility, thus reducing I_{on} . The large vertical electric field required to form an inversion layer also significantly reduces the mobility, through interface roughness scattering [2]. A substantial volume of research is therefore focused on investigating new high-mobility channel materials to improve the drive current at lower voltages [28], [29]. Alternatively, the problem can be circumvented by developing a range

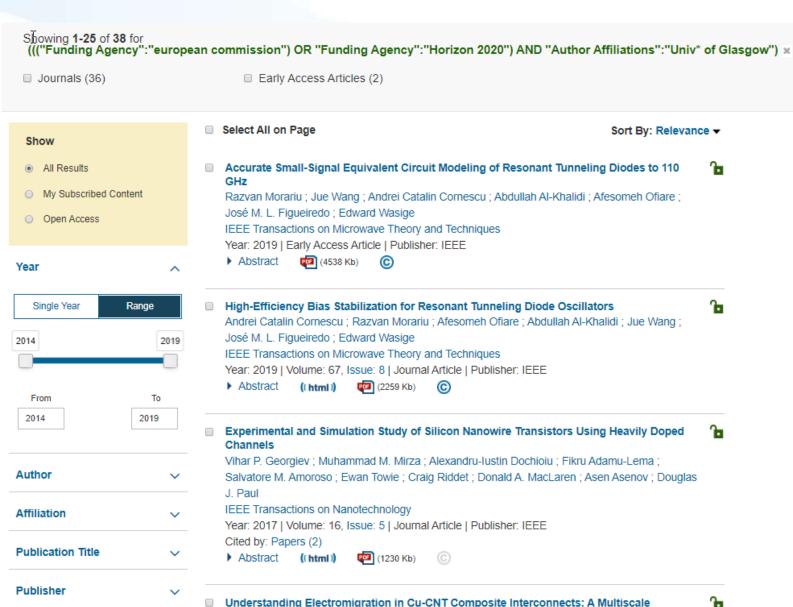
Searching by funding agency

Boolean operators:

- 1. OR
- 2. AND



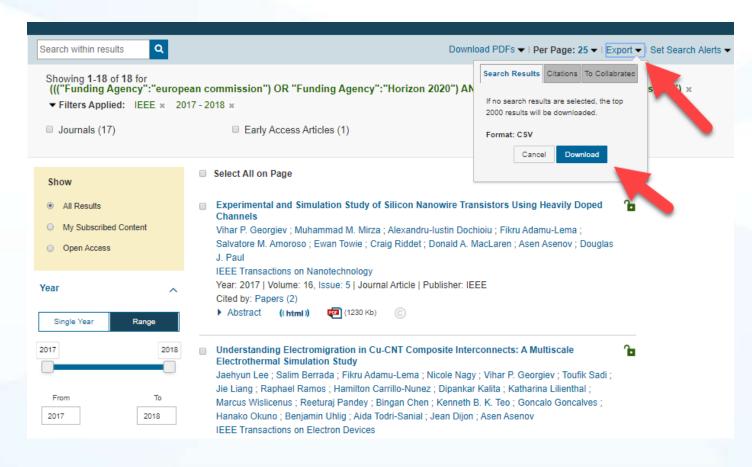




Search results can be filtered by OA status, publisher, content type, and year.

Only articles published in IEEE journals are eligible to use institutional funds.





- Results can be exported from the search results page by clicking on "Export" in the top right.
- Exports are limited to 2,000 results.

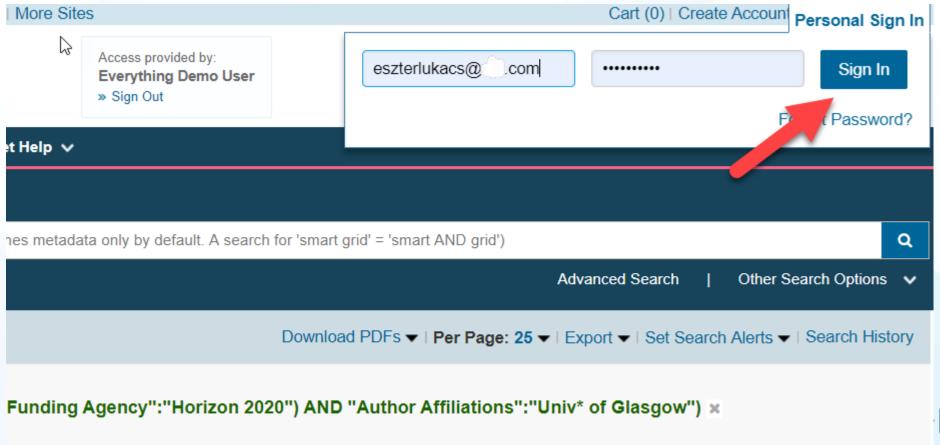


7	Α	В	C	D	E	F	G	Н	1	J	K
1	Document	Authors	Author Affiliations	Publicatio	Date Adde	Publicatio	Volume	Issue	Start Page	End Page	Abstract
2	Experimer	V. P. Georgi	School of Engineering, University of Glasgow, Glasgow, U.K	IEEE Trans	actions on	2017	16	5	727	735	The experi
3	Understar	J. Lee; S. Ber	School of Engineering, University of Glasgow, Glasgow, U.K	IEEE Trans	actions on	2018	65	9	3884	3892	In this pap
4	Atomistic-	J. Liang; J. Le	Microelectronics Department, CNRS-LIRMM/University of I	IEEE Trans	actions on	2018	17	6	1084	1088	In this pap
5	15-Gb/s 5	J. Wang; A. /	High Frequency Electronics Group, University of Glasgow, G	IEEE Trans	actions on	2018	66	11	4698	4705	This paper
6	Variability	R. Chen; J. Li	Microelectronics Department, Montpellier Laboratory of Co	IEEE Trans	actions on	2018	65	11	4955	4962	In this pap
7	Variability	R. Chen; J. Li	Microelectronics Department, LIRMM, CNRS, University of	IEEE Trans	actions on	2018	65	11	4963	4970	In this pap
8	Simulation	T. Al-Ameri;	Device Modelling Group, School of Engineering, University	IEEE Journ	al of the El	2017	5	6	466	472	In this pap
9	Modeling	A. Vilouras;	Bendable Electronics and Sensing Technologies Group, Elec	IEEE Trans	actions on	2017	64	5	2038	2046	The field o
10	Epitaxial D	R. Baba; B. J	University of Glasgow, Glasgow, U.K.; University of Sheffiel	IEEE Journ	al of Quan	2018	54	2	1	11	We discus
11	Possibilitie	M. Rizwan; ,	Department of Electronics and Communications Engineerin	IEEE Anter	nnas and W	2017	16		1828	1831	This letter
12	Radio Reso	H. Malik; H.	Thomas Johann Seebeck Department of Electronics, Tallinn	IEEE Acces	is	2018	6		15051	15064	Narrowba
13	Speech Sy	M. P. Aylett	School of Informatics, University of Edinburgh, Edinburgh,	IEEE Trans	actions on	2017	PP	99	1	1	A synthet
14	Distribute	K. Kolomvat	Department of Informatics and Telecommunications, University	IEEE Interr	net of Thing	2017	4	1	183	191	We focus
15	TiO2-Base	M. Simić; I	Faculty of Electrical Engineering, University of Banja Luka, E	IEEE Senso	ors Journal	2017	17	2	248	255	Miniaturiz
16	Electroma	Y. A. Sambo	Department of Electrical and Computer Engineering, Baze U	IEEE Trans	actions on	2017	66	9	8212	8222	The increa
17	Gate Leak	J. L. Padilla;	Depto. de Electrónica y TecnologÃ-a de los Computadores	IEEE Trans	actions on	2018	65	10	4679	4686	Among th
18	Unlocking	C. Galiotto;	CONNECT Centre, Trinity College Dublin, Dublin, Ireland; Bro	IEEE Acces	s	2018	6		11793	11803	Spectrum
19	High Perfo	B. Sakthivel:	Department of Physics. Thin Film Lab. National Institute of	IEEE Senso	ors Journal	2017	17	20	6529	6536	Here. we r

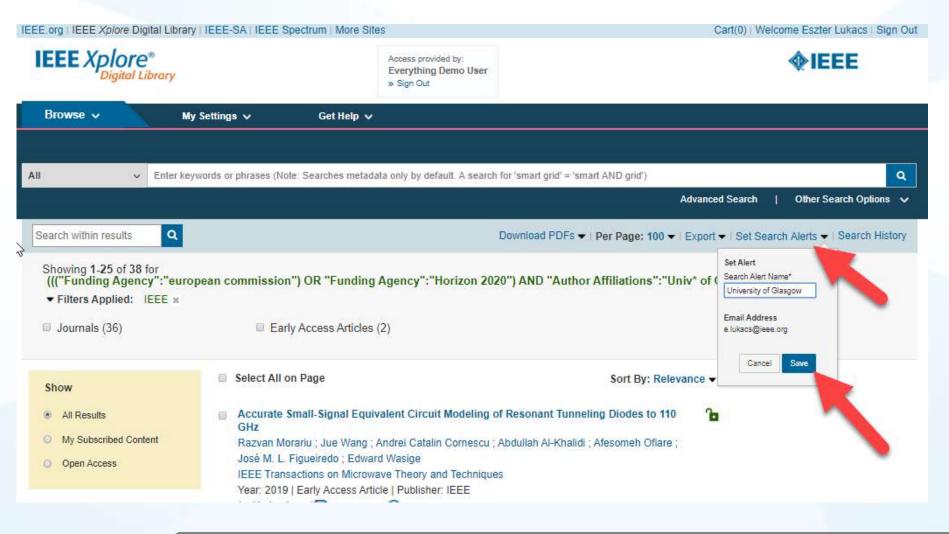
Results will be exported in the specified format.



■ To set a search alert, the administrator will first need to sign in with personal user account to IEEE *Xplore*.

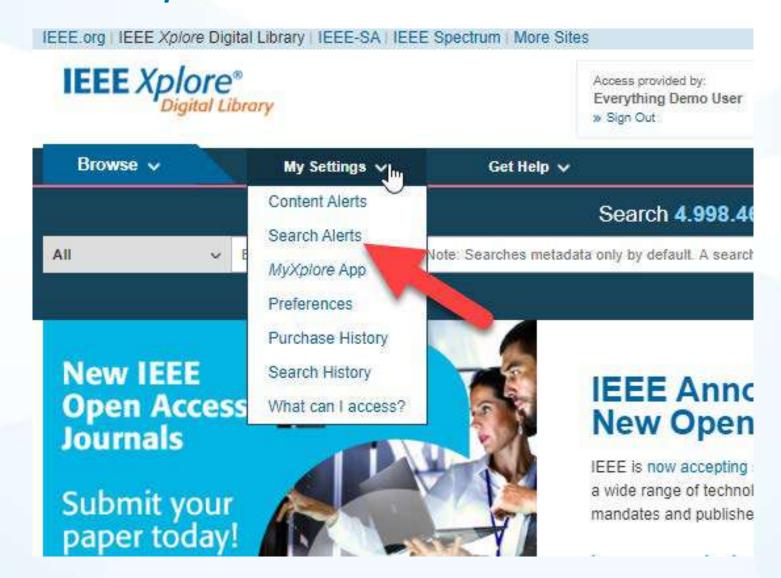






- Then, conduct a search.
- Once the results come up, click "Set Search Alerts" in the top right.
- Enter a name for the search.

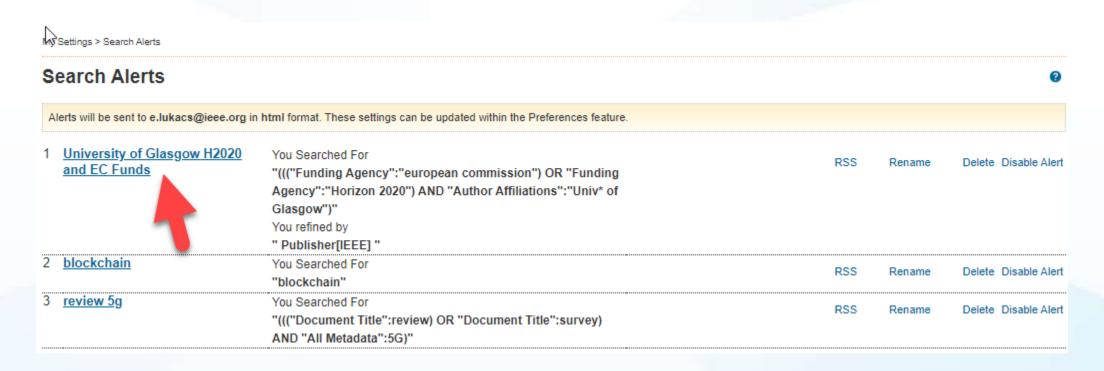




To access saved searches, click on "My Settings," and "Search Alerts."



A list of saved searches will be displayed.





Need additional assistance?

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